

**6-INCH 300-MICRON THIN P-TYPE SILICON WAFER**  
**Si-Wafer 6P0/FZ/5k-8k/300±25/DSP/TTV<10**

**Item Nr. J16374**



**Specifications:**

- Diameter : 150 ±0.3 mm
- Material : Silicon
- Growth : FZ
- Grade : Prime
- Type/Dopant : P-type/Boron
- Orientation : <100> ±0.5°
- Resistivity : 5,000-8,000 Ohm-cm
- Thickness : 300 ±25 µm
- Surface Finish : Double Side Polished
- Flats : 1 Primary Flat, SEMI-Std.
- Primary Flat Length : 57.5 ±2.5 mm
- Primary Flat Location : @{110} ±1°
- TTV : <10 µm
- Bow : <25 µm
- Warp : <30 µm
- Particles ≥0.3 µm : <15
- Packaging : Cassettes

